



3D Packaging and Integration Japan TC Chapter

Japan Standards Fall Meetings 2024

Monday, October 28, 2024

Room 1, SEMI Japan, Tokyo, Japan/ Official Virtual TC Chapter Meeting

14:00–17:00 (JST)

AGENDA

1 Welcome/Call to Order

- 1.1 Introductions
- 1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)
- 1.3 Agenda Review

2 Review of Previous Meeting Minutes

3 Liaison Report

- 3.1 JRSC Report
- 3.2 GCS Report
- 3.3 North America TC Chapter
- 3.4 Taiwan TC Chapter

4 Staff Report

5 Ballot Review

- 5.1 Doc.#7252, Reapproval of SEMI 3D19-0619, Test Method for Adhesive Strength of Adhesive Tray Used for Thin Chip Handling
- 5.2 Doc.#7253, Reapproval of SEMI G96-1014 (Reapproved 1019), Test Method for Measurement of Chip (Die) Strength by mean of Cantilever Bending

6 Subcommittee & Task Force Reports

- 6.1 3DS IC Bonded Layer Inspection Metrology Task Force
- 6.2 Wafer Bond Strength Measurement by Double-cantilever Beam Task Force
- 6.3 3D Packaging & Integration 5-Year Review Task Force



6.4 3D Packaging & Integration Steering Group

7 Old Business

7.1 Project Period Review

7.2 5-Year Review

8 New Business

9 Action Item Review

9.1 Open Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
3DP&I_20240523-01	SEMI Staff	To send SNARF for New Standard, Guide for 3DS IC bonded layer inspection metrology for 3DP&I GTC members' 2 weeks review.
3DP&I_20240523-02	3DP&I 5-Year Review TF	To submit Doc.#7252 (G96 Reapproval ballot) and Doc.#7253 (3D19 Reapproval ballot) for Cycle 6.
3DP&I_20240523-03	Co-chairs SEMI Staff	To have a discussion regarding a SEMICON Japan program.

9.2 New Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>

10 Next Meeting and Adjournment